



Material Content Data Sheet



Sales Product Name		BSC027N04LS G		Issued		4. July 2019		
MA#		MA005337494						
Package		PG-TDSON-8-1		Weight*		120.66 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.391	1.98	1.98	19817	19817
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		94	
	non noble metal	iron	7439-89-6	0.038	0.03		313	
	non noble metal	copper	7440-50-8	37.762	31.30	31.34	312948	313355
	non noble metal	copper	7440-50-8	0.042	0.03	0.03	345	345
wire	non noble metal	copper	7440-50-8	0.042	0.03	0.03	345	345
encapsulation	organic material	carbon black	1333-86-4	0.083	0.07		689	
	plastics	epoxy resin	-	6.570	5.44		54450	
	inorganic material	silicondioxide	60676-86-0	34.930	28.95	34.46	289483	344622
leadfinish	non noble metal	tin	7440-31-5	1.452	1.20	1.20	12030	12030
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1372	1372
solder	non noble metal	tin	7440-31-5	0.046	0.04		377	
	noble metal	silver	7440-22-4	0.057	0.05		471	
	non noble metal	lead	7439-92-1	2.173	1.80	1.89	18008	18856
heatspreader	inorganic material	phosphorus	7723-14-0	0.003	0.00		28	
	non noble metal	iron	7439-89-6	0.011	0.01		94	
	non noble metal	copper	7440-50-8	11.320	9.38	9.39	93814	93936
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		55	
	non noble metal	iron	7439-89-6	0.022	0.02		185	
	noble metal	silver	7440-22-4	1.289	1.07		10686	
	non noble metal	copper	7440-50-8	22.292	18.47	19.57	184741	195667
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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